

# APPLICATION DATA SHEET

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<b>Title of Invention</b>	METHOD OF FABRICATING CONTACT HOLES ON A SEMICONDUCTOR CHIP
<b>Application Type :</b> regular, utility <b>Attorney Docket Number :</b> NTCP0006USA	
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as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.